

# Digital VLSI Design

## Lecture 1: Introduction

Semester A, 2016-17

Lecturer: Dr. Adam Teman

6 November 2016



Emerging Nanoscaled  
Integrated Circuits and Systems Labs



Bar-Ilan University  
אוניברסיטת בר-אילן

Disclaimer: This course was prepared, in its entirety, by Adam Teman. Many materials were copied from sources freely available on the internet. When possible, these sources have been cited; however, some references may have been cited incorrectly or overlooked. If you feel that a picture, graph, or code example has been copied from you and either needs to be cited or removed, please feel free to email [adam.teman@biu.ac.il](mailto:adam.teman@biu.ac.il) and I will address this as soon as possible.

# Motivation

United States Patent Office 3,138,743  
Patented June 23, 1964

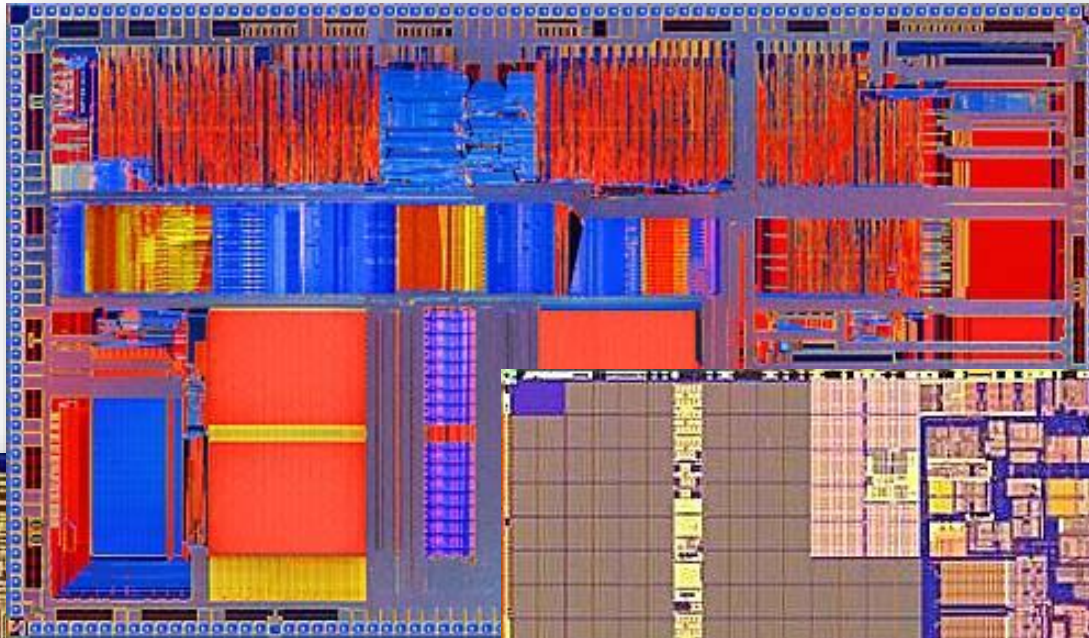
1  
3,138,743  
MINIATURIZED ELECTRONIC CIRCUITS  
Jack S. Kilby, Dallas, Tex., assignor to Texas Instruments Incorporated, Dallas, Tex., a corporation of Delaware  
Filed Feb. 6, 1959, Ser. No. 791,602  
25 Claims. (Cl. 317-101)

2  
This invention relates to miniature electronic circuits, and more particularly to unique integrated electronic circuits fabricated from semiconductor material.

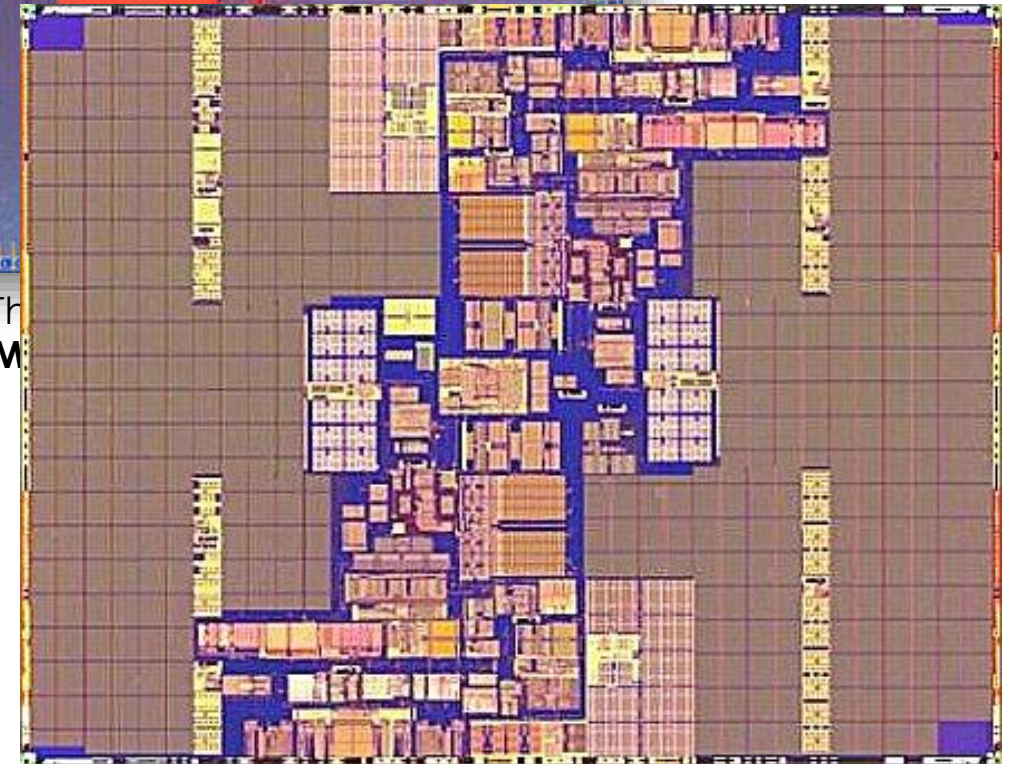
10 Many methods and techniques for miniaturizing electronic circuits have been proposed in the past. At first, most of the effort was spent upon reducing the size of the components and packing them more closely together. Work directed toward reducing component size is still going on but has nearly reached a limit. Other efforts have been made to reduce the size of electronic circuits such as by eliminating the protective coverings from components by using more or less conventional

15 tion can best be attained by use of as few materials and operations as possible. In accordance with the principles of the invention, the ultimate in circuit miniaturization is attained using only one material for all circuit elements and a limited number of compatible process steps for the production thereof.

The above is accomplished by the present invention by utilizing a body of semiconductor material exhibiting one type of conductivity, either n-type or p-type, and having formed therein a diffused region or regions of appropriate conductivity type to form a p-n junction between such region or regions and the semiconductor body or, as the case may be, between diffused regions. According to the principles of this invention, all components of an entire electronic circuit are fabricated within the body so characterized by adapting the novel techniques to be described in detail hereinafter. It is to be noted that all components of the circuit are integrated into the body of semiconductor material and constitute portions thereof.



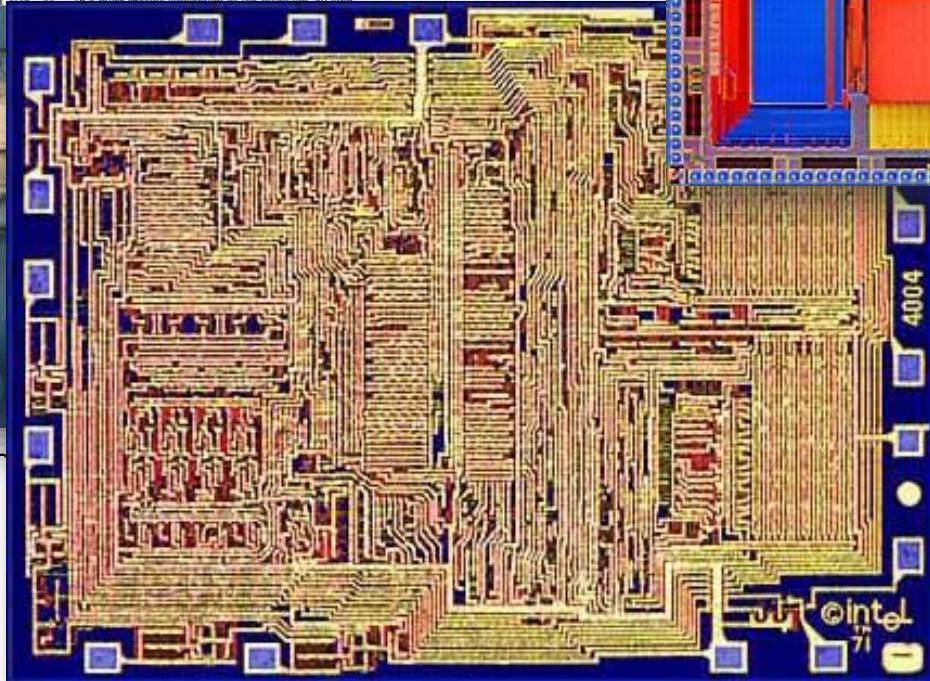
1992 – The  
1.2M



2006 – Itanium 2 “Montecito”  
1.7B Transistors



1964 – The In

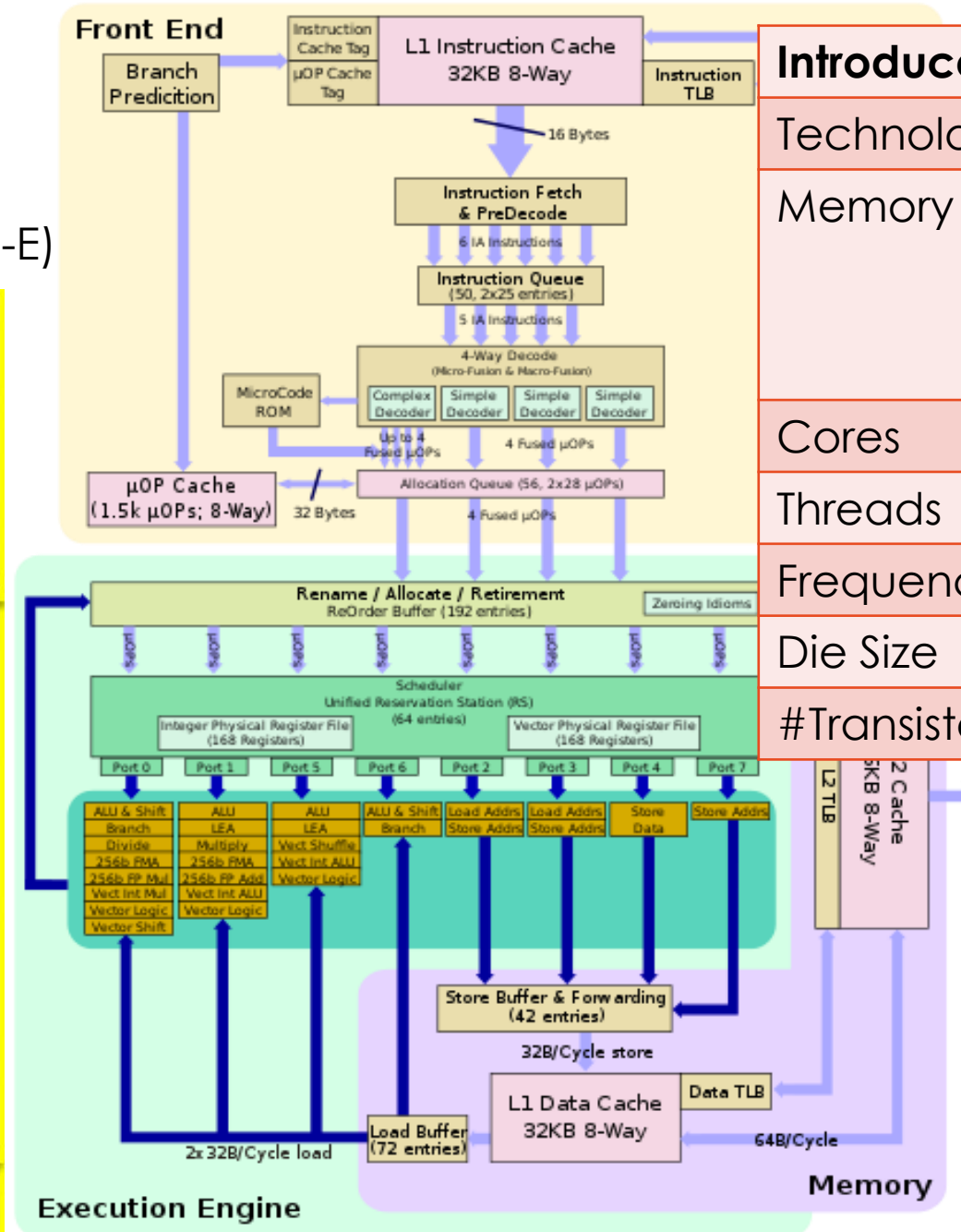
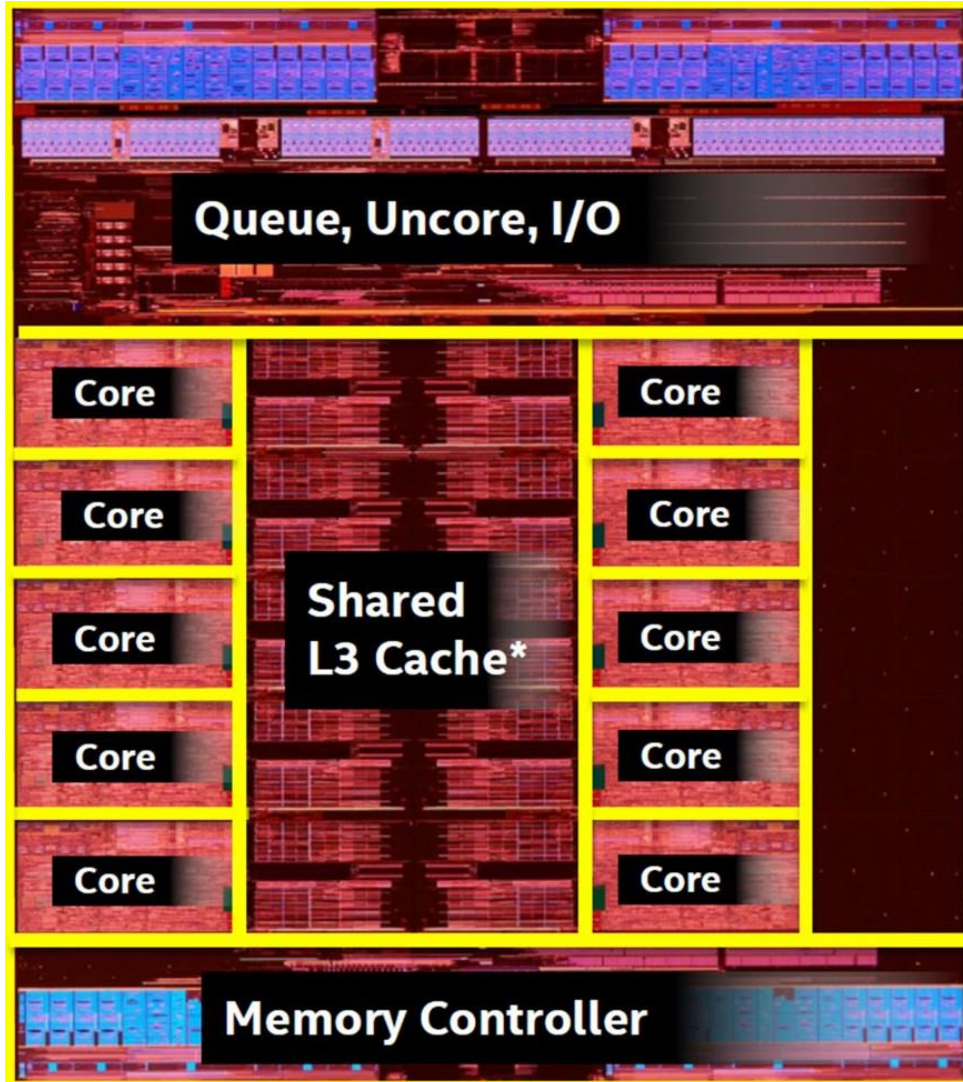


1971 – The Intel 4004  
2,300 Transistors



# Motivation

Core i7-6950X Extreme Edition (Broadwell-E)

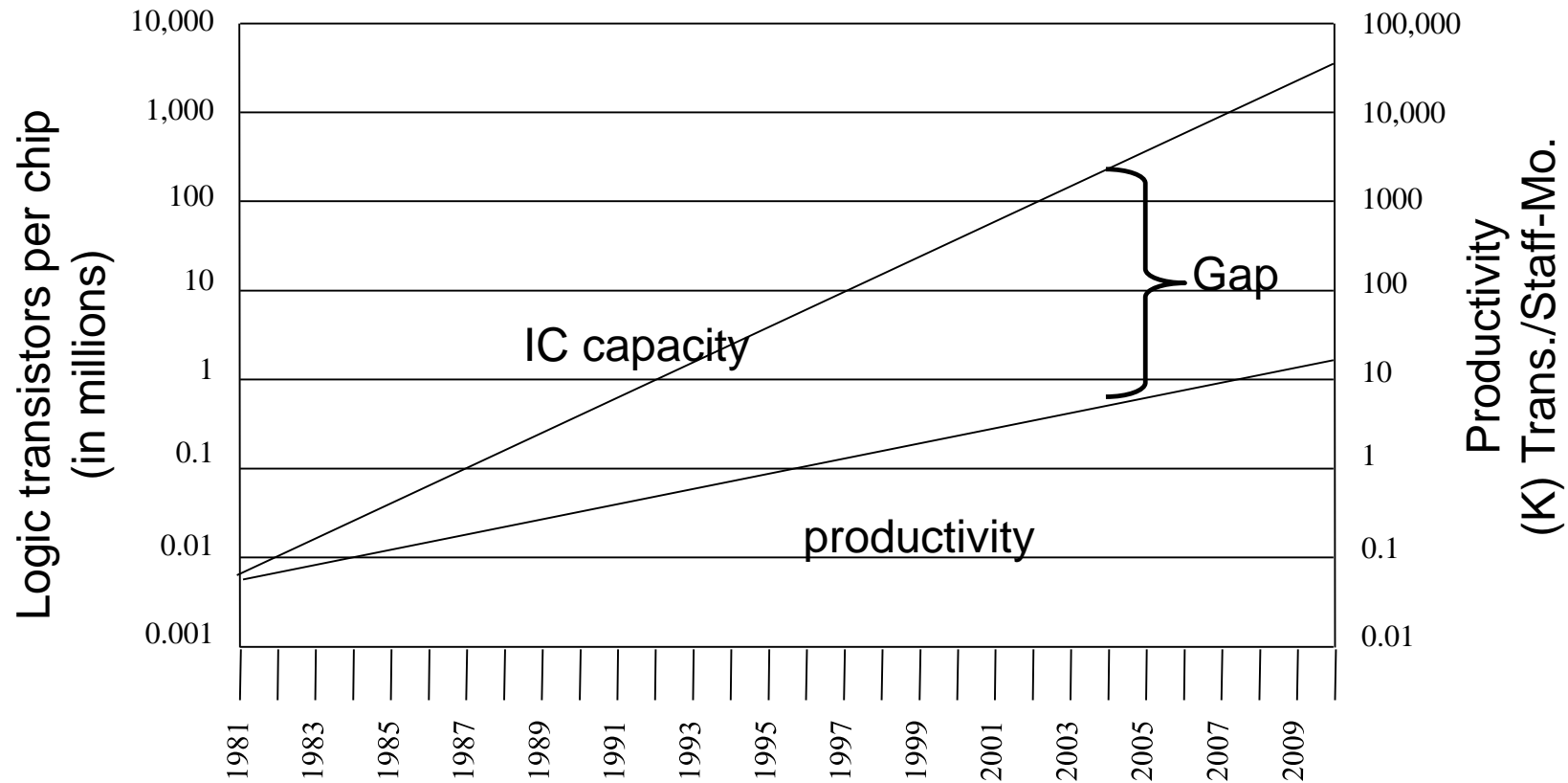


Introduced	May 2016
Technology	14nm FinFET
Memory	320KB L1-I\$ 320KB L1-D\$ 2.56MB L2\$ 25MB L3\$
Cores	10
Threads	20
Frequency	3.0-3.5 GHz
Die Size	246 mm <sup>2</sup>
#Transistors	3.2 B

[http://en.wikichip.org/wiki/intel/core\\_i7ee/i7-6950x](http://en.wikichip.org/wiki/intel/core_i7ee/i7-6950x)

# Motivation

- Houston, we have a problem...

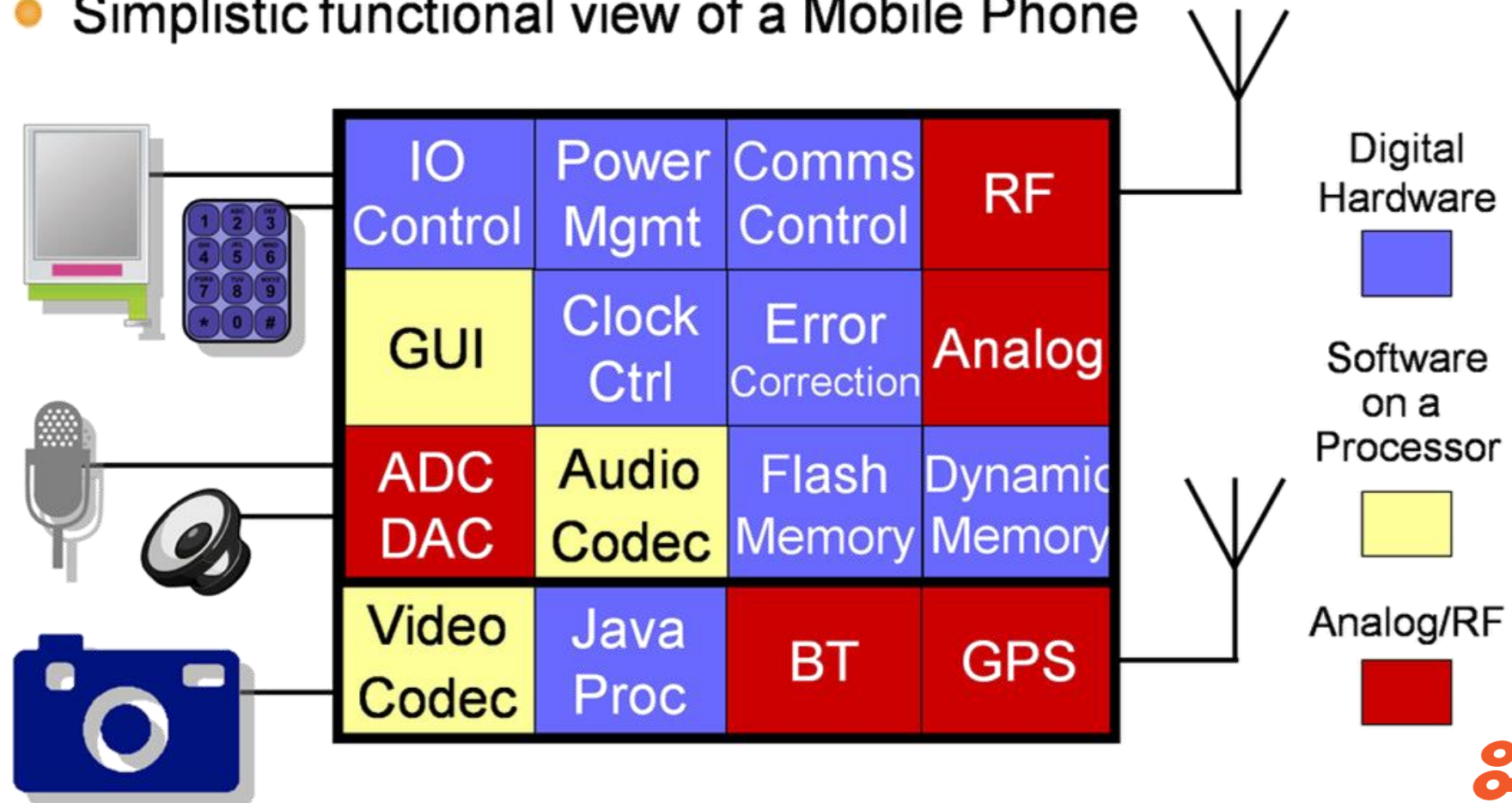


“Moore’s Law of Engineers”

# Motivation

- How on earth do we design such a thing???

- Simplistic functional view of a Mobile Phone



# The Solution:

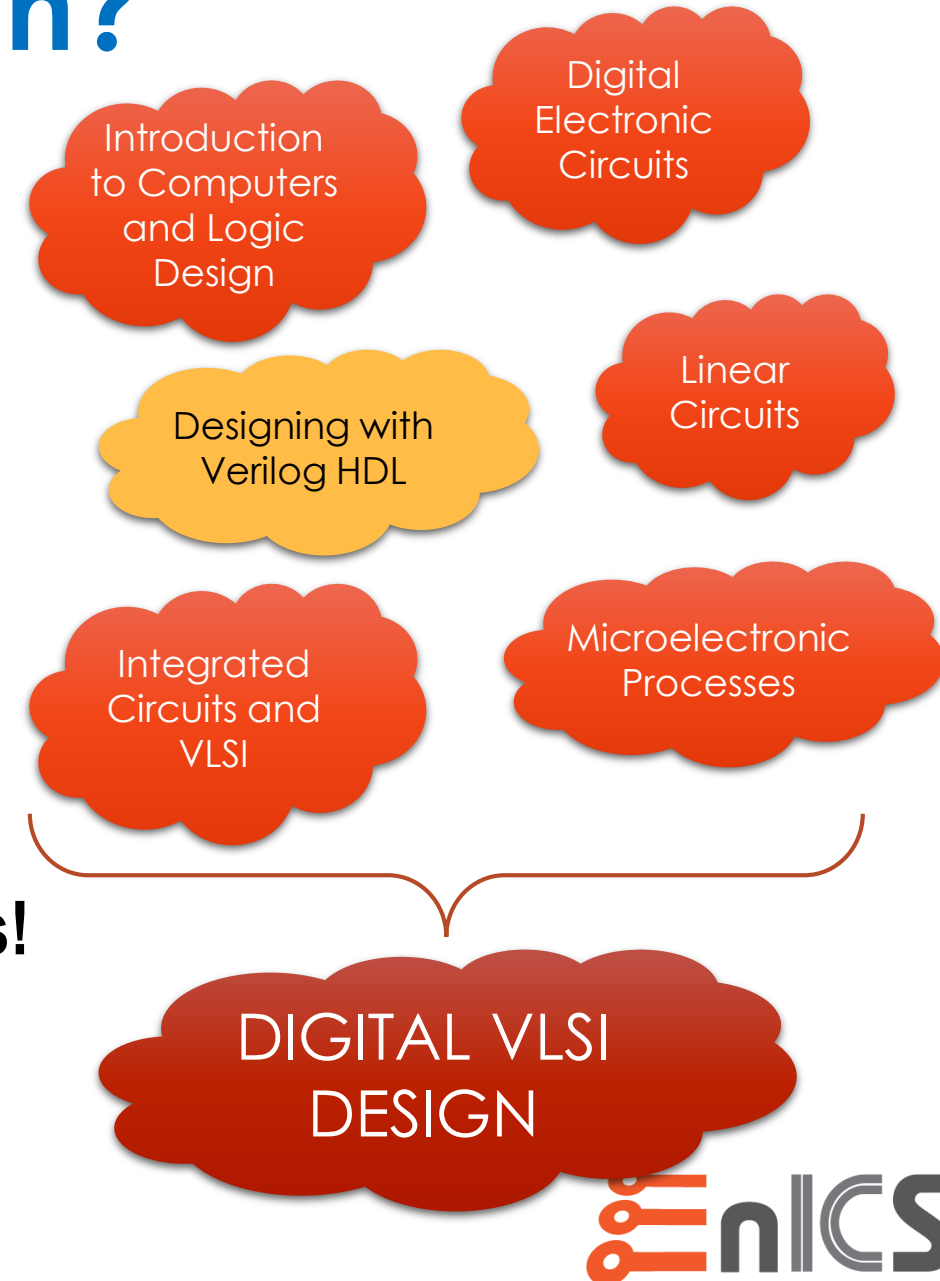
Design  
Abstraction

Design  
Automation

Design  
Re-use (IP)

# Where does this course fit in?

- In this course, we will learn how to design a chip.
- You have already learned:
  - Build a general purpose micro-processor.
  - How to design a digital gate, analog circuit, and custom-designed component.
  - How to fabricate a chip.
- Now, we will learn how to fit all of these on a chip  
...and make sure it works!





# Course Logistics



# Course Info

- **Course number:** 83-612, Semester A, 2016-17
  - Hebrew name: מעגלי ומערכות וי.אל.אס.איי. דיגיטליים
  - More appropriate name: Digital VLSI Design
  - 1.5 Credits (2 hrs. Lecture + 1 hr. Discussion/Exercise)
- **Lectures:** Tuesday 09:00-11:00 – Auditorium 2
  - Actual times: 09:05-10:35
  - Lecture will be 1.5 hours with no break
- **Discussion/Exercise:** Tuesday 11:00-12:00 – Room 42
  - Actual times: 11:00-11:45+
- **Presentations and Discussion Handouts** will be available before the lecture.
  - You are advised to print out the handouts!
- **Video** will hopefully be available *before* the lecture...

# Course Administration

- **Lecturer:**

- Dr. Adam Teman – but call me Adi.
- Office Hours:
  - Faculty of Engineering, 4<sup>th</sup> Floor, Office 413
  - Tuesday 1300-1400, but please make appointment by email
  - Contact: [adam.teman@biu.ac.il](mailto:adam.teman@biu.ac.il)

- **Teaching Assistant:**

- Or Maltabashi
- Office Hours:
  - EnICS Labs, Floor -1, Room 62 – **by appointment!**
  - Contact: [ormaltab@gmail.com](mailto:ormaltab@gmail.com)

- **USE THE FORUM!!!**

- ***Google and Cadence Support are your best friends!***

If you have not yet opened a Cadence Support account, now is the time!



# Homework/Projects

- **Homework:**

- Almost every week, you will receive a homework assignment.
- Deadline for homework is (usually) 2 weeks from publication.
  - **Extensions** will be considered **IFF** you ask *at least* 48 hours before the deadline!
- Homework is done ***individually!***
  - Helping each other is encouraged.
  - **Grading** will be according to the ***order*** of submission!

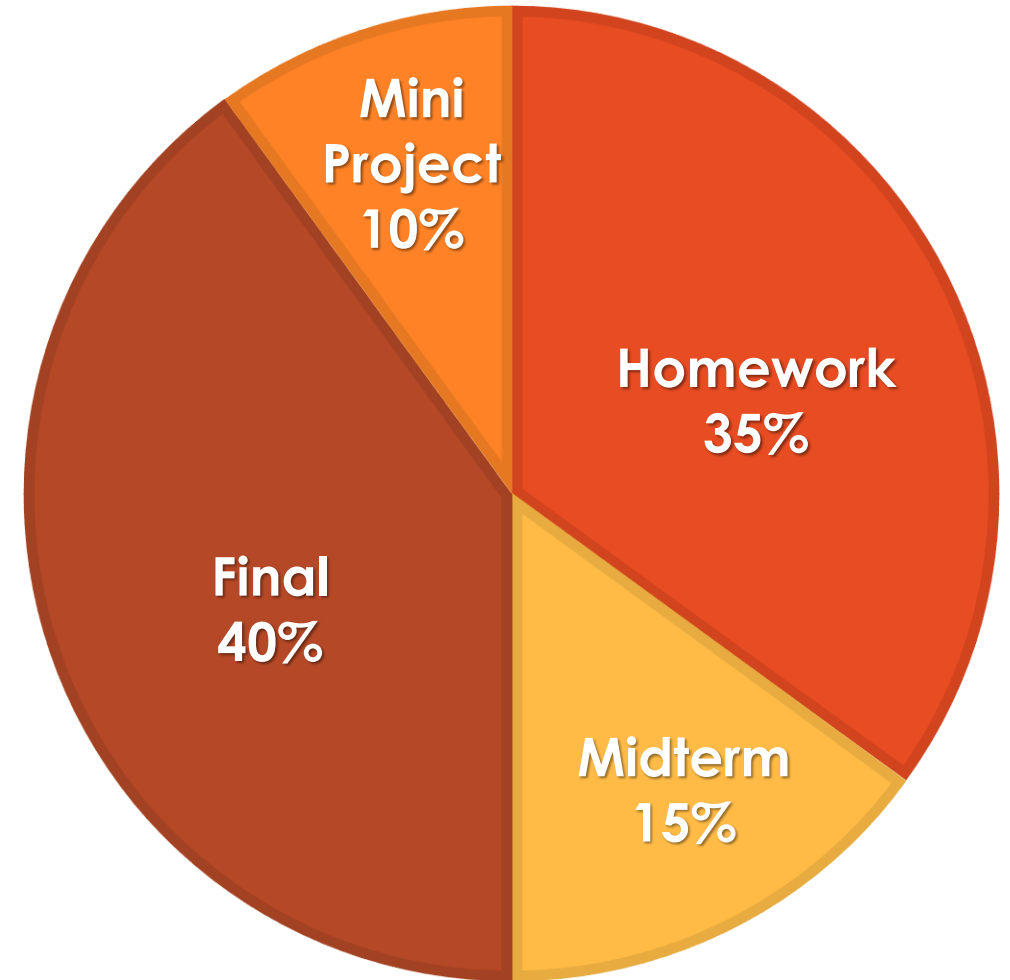
- **Mini-project:**

- Each pair of students will suggest a subject for a project towards the end of the semester.
- Adi will authorize the project subject.
- Bonus for preparing in LaTeX and/or making a video!

# Grading

- **Homework: 35%**
- **Midterm: 15%**
- **Final: 40%**
  - Both the midterm and final will include *many* short questions, often multiple-choice, covering *everything* we discussed in class.
- **Mini-project: 10%**
  - Bonus for preparing in LaTeX!

## GRADE



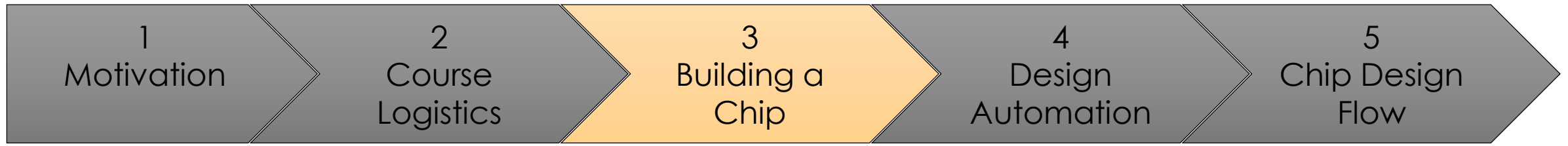


# Syllabus (*not Final*)

- **Week 1: Introduction**
- **Week 2: Verilog**
- **Week 3: Static Timing Analysis**
- **Week 4-5: Logic Synthesis**
- **Week 6: Moving to the Physical Domain**
- **Week 7: Placement**
- **Week 8: Clock Tree Synthesis**
- **Week 9: Routing**
- **Week 10: Design for Test**
- **Week 11: Verification**

# References

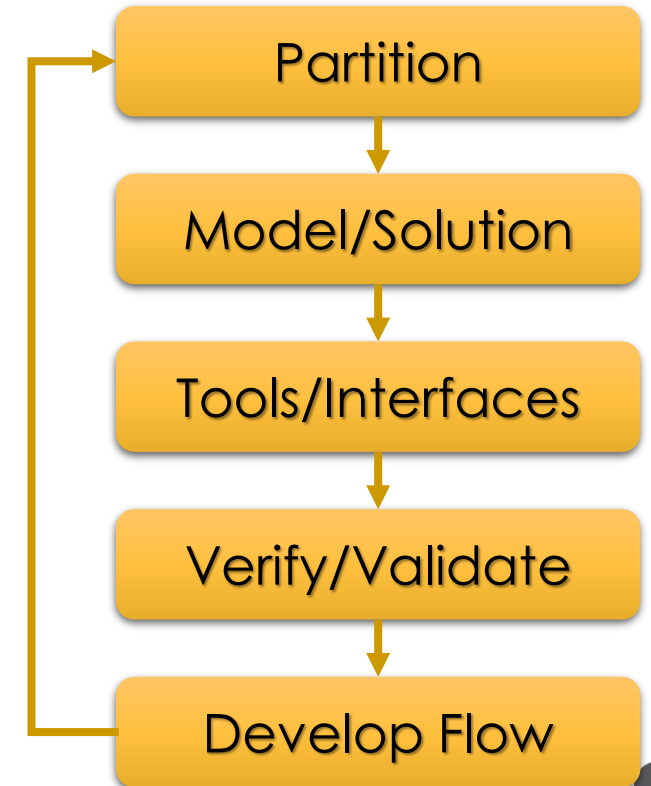
- **Way too many to state all, and hopefully many are cited on the slides themselves, but here are a few:**
  - Rob Rutenbaur – “From Logic to Layout” (available on Coursera)
  - Nir Sever – Low Power Design (BGU)
  - Roy Shor – תכן לוגי (BGU)
  - IDESA Digital Design Course
  - Rabaey “Digital Integrated Circuits” 2<sup>nd</sup> Edition
  - Weste, Harris “CMOS VLSI Design”
  - Google (oh, thank you Google!)
  - Cadence Support ([support.cadence.com](http://support.cadence.com))
  - Synopsys SolveNet ([solvenet.synopsys.com](http://solvenet.synopsys.com))



# Building a Chip

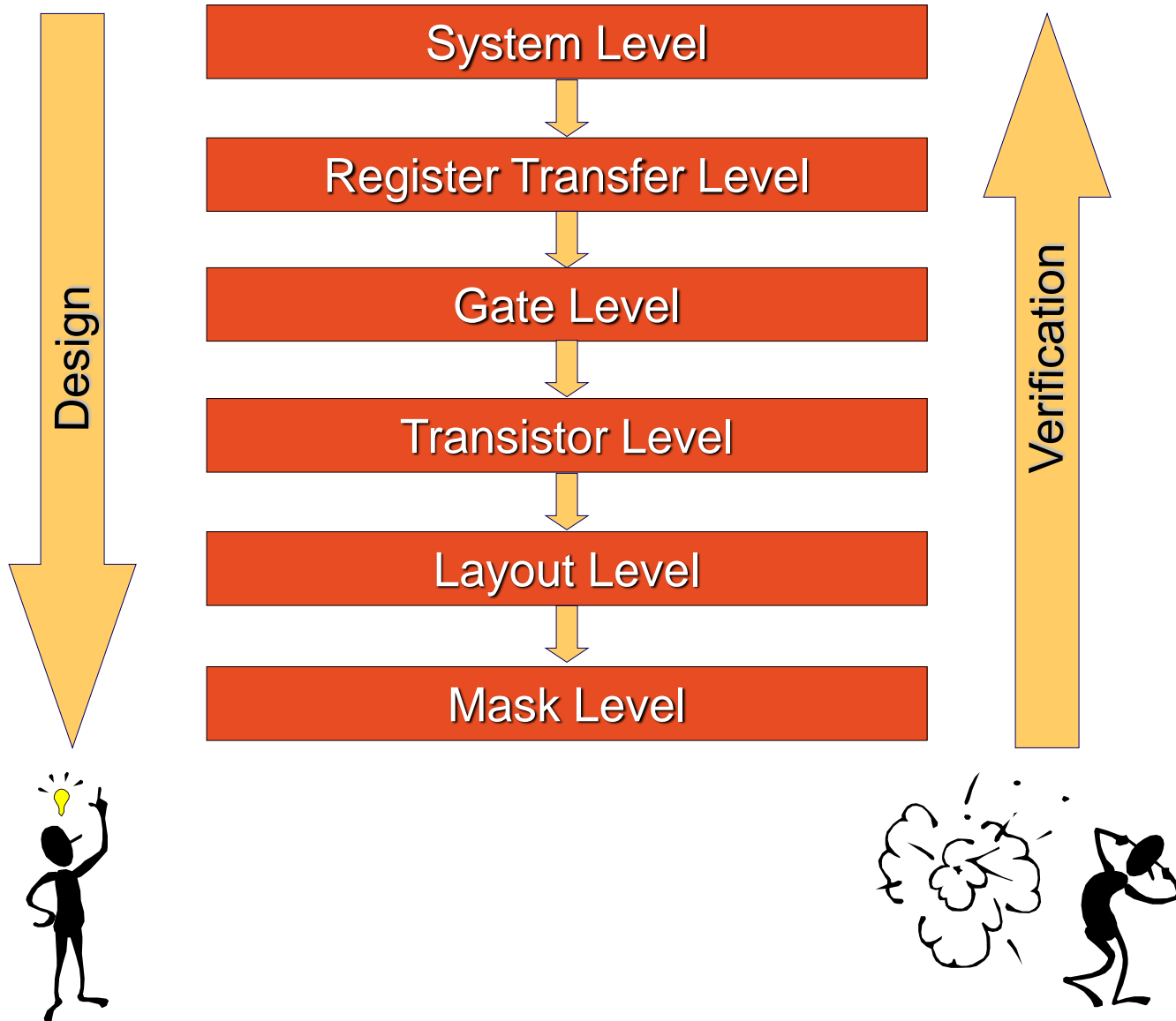
# General Design Approach

- How do engineers build a bridge?
- **Divide and conquer !!!!**
  - **Partition** design problem into many sub-problems, which are manageable
  - Define mathematical **model** for sub-problem and find an **algorithmic** solution
    - Beware of model limitations and check them !!!!!!!
  - Implement algorithm in **individual design tools**, define and implement general **interfaces** between the tools
  - Implement **checking tools** for boundary conditions
  - Concatenate design tools to general **design flows** which can be managed
  - See what doesn't work and **start over**.





# Basic Design Abstraction



Another view:

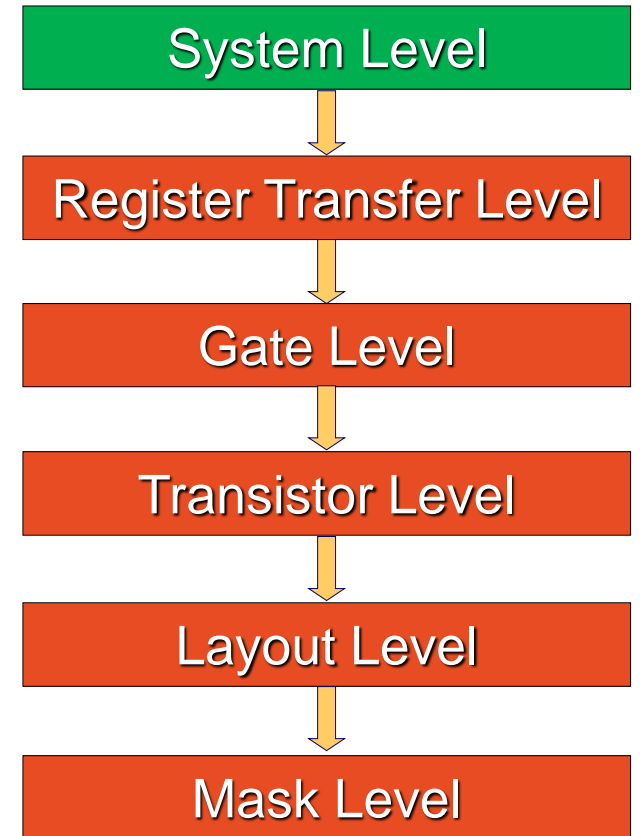


# System Level Abstraction

- **Abstract algorithmic description of high-level behavior**
  - e.g., C-Programming language

```
Port* compute_optimal_route_for_packet
(Packet_t *packet, Channel_t *channel)
{
    static Queue_t *packet_queue;
    packet_queue = add_packet(packet_queue, packet);
    ...
}
```

- Abstract because it does not contain any implementation details for timing or data
- Efficient to get a compact execution model as a first design draft
- Difficult to maintain throughout project because no link to implementation

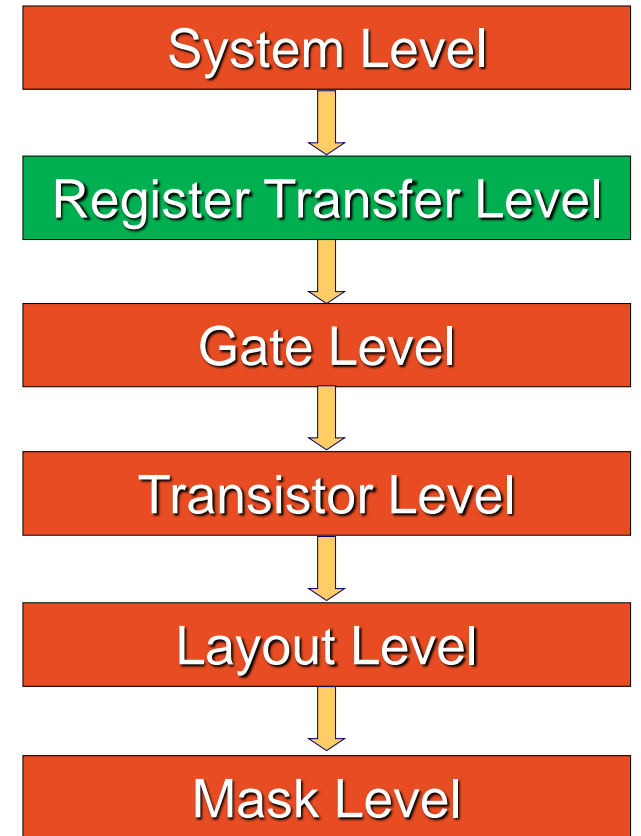


# Register-Transfer Level (RTL)

- **Cycle accurate model “close” to the hardware implementation**
  - bit-vector data types and operations as abstraction from bit-level implementation
  - sequential constructs (e.g., if-then-else, while loops) to support modeling of complex control flow

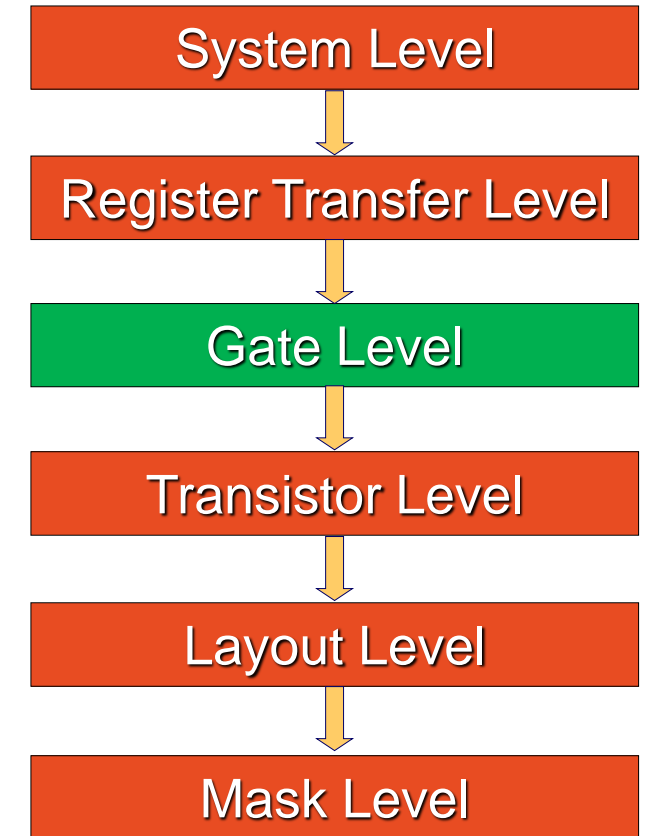
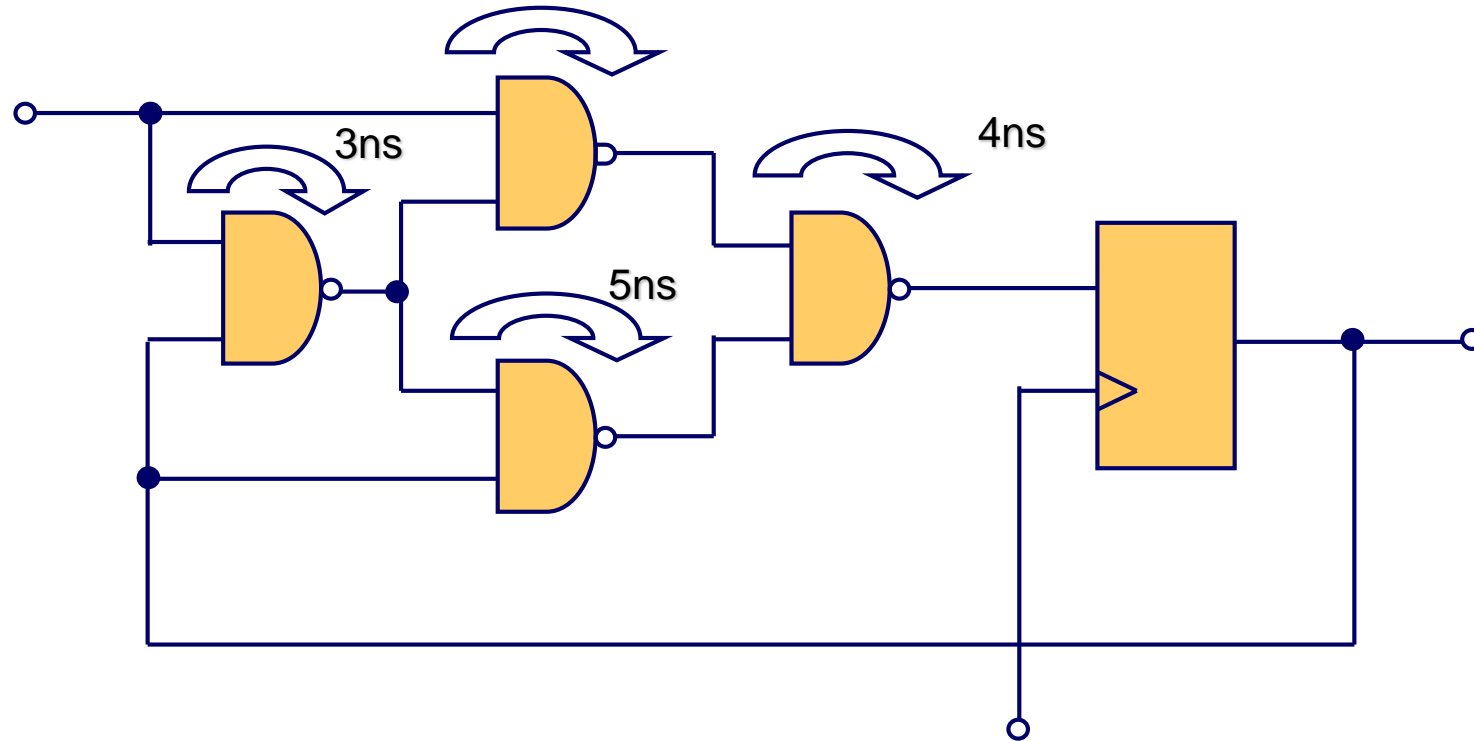
```
module mark1;
  reg [31:0] m[0:8192];
  reg [12:0] pc;
  reg [31:0] acc;
  reg[15:0] ir;

  always
  begin
    ir = m[pc];
    if(ir[15:13] == 3b'000)
      pc = m[ir[12:0]];
    else if (ir[15:13] == 3'b010)
      acc = -m[ir[12:0]];
    ...
  end
endmodule
```



# Gate Level Abstraction (GTL)

- **Model on finite-state machine level**
  - models function in Boolean logic using registers and gates
  - various delay models for gates and wires

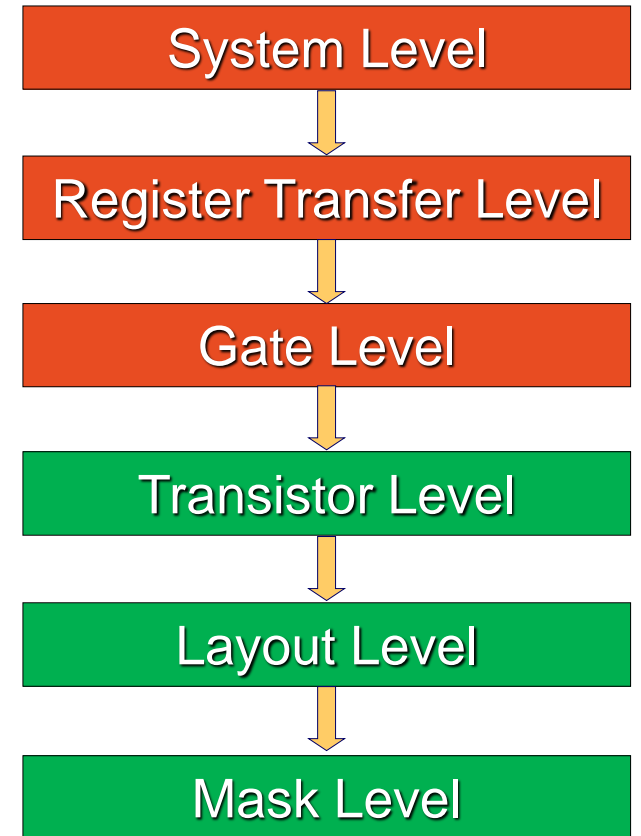
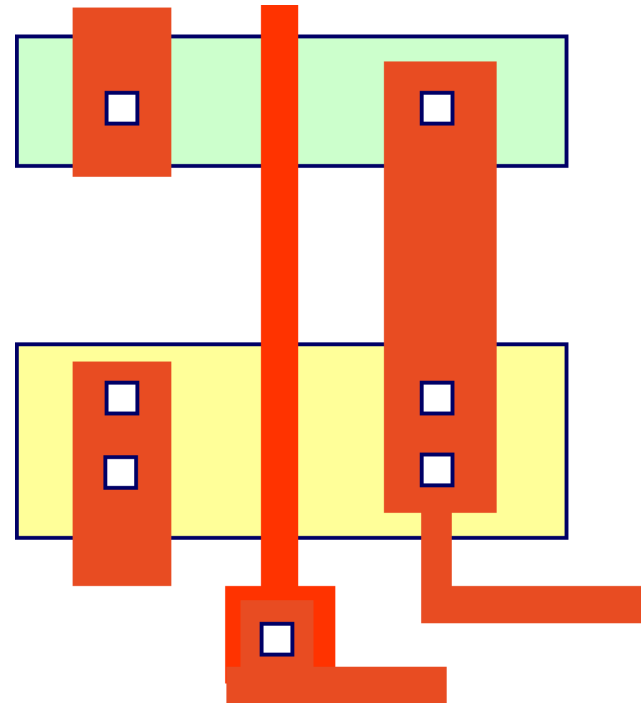




# Transistor to Mask Level

- **As we've seen in previous courses:**

- Transistor Level:
  - Use compact models to enable accurate circuit simulation.
- Layout Level:
  - Draw polygons to implement the devices and interconnect.
- Mask Level:
  - Create actual photo-masks for performing lithography during fabrication process.

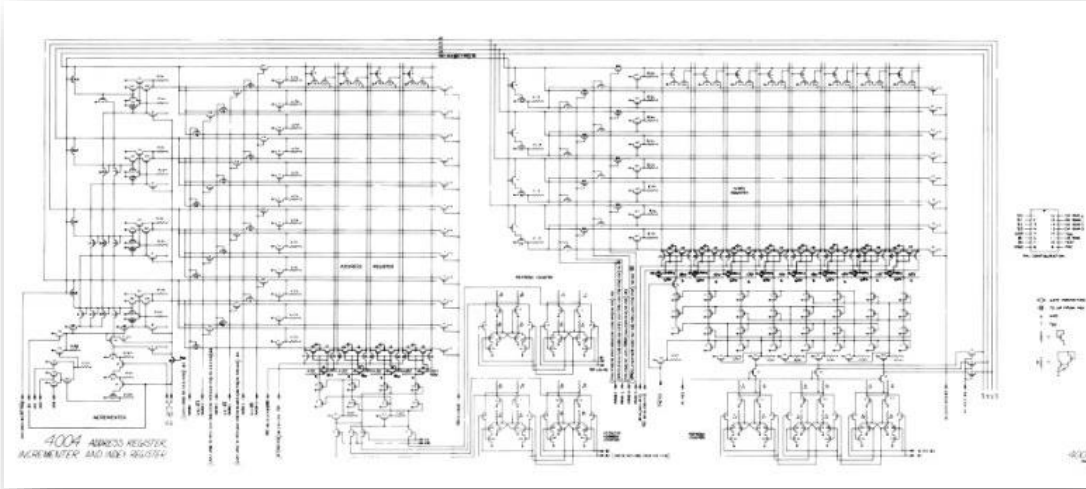




# Design Automation

# The (really) Olden Days

- Early chips were prepared entirely by hand:



Schematic of Intel 4004 (1971)

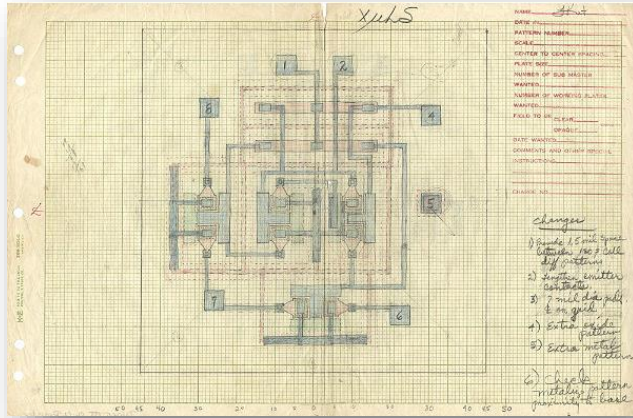


Mainframe CAD System (1967)

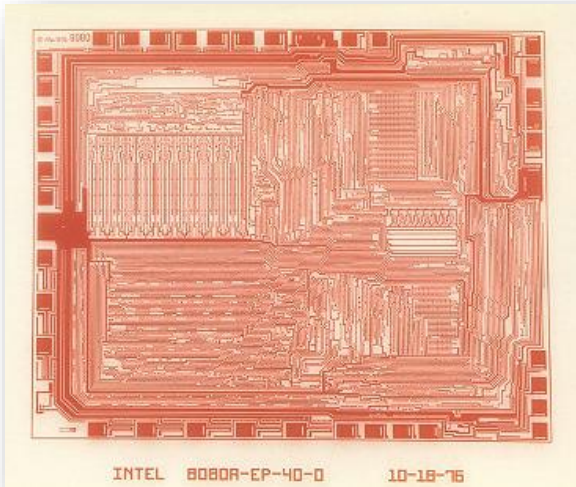


# The (really) Olden Days

- Early chips were prepared entirely by hand:



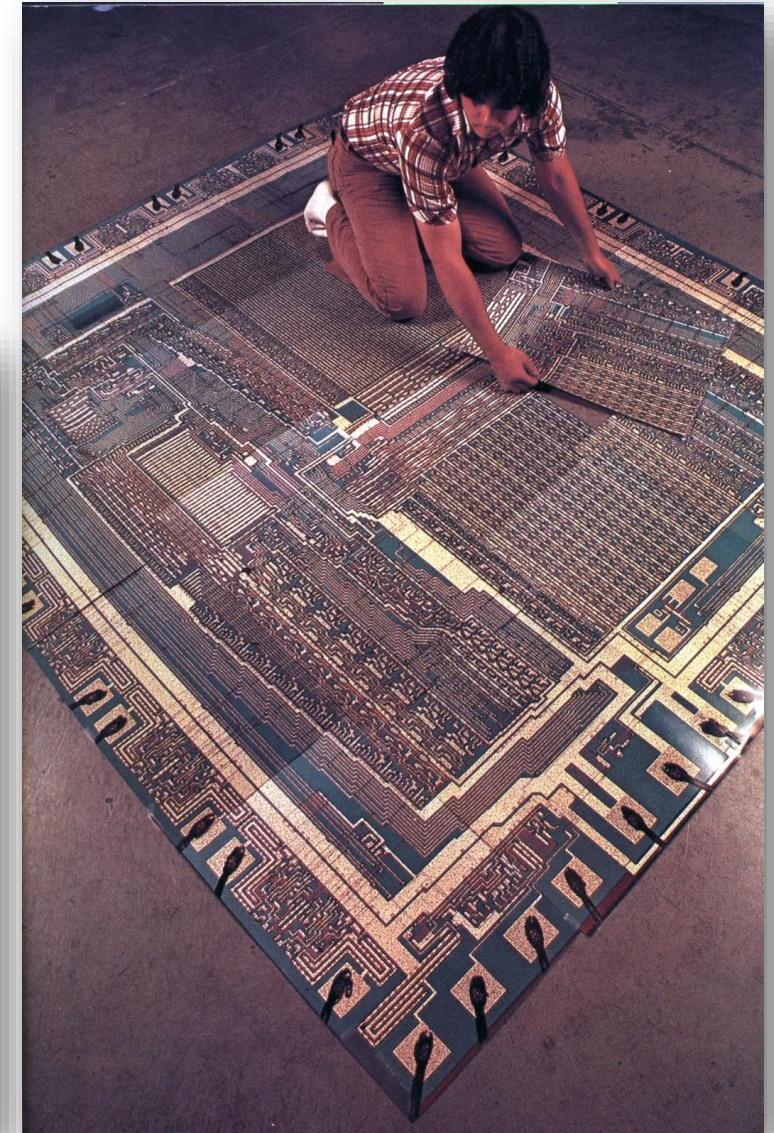
Hand drawn gate layout (Fairchild)



8088A Mask Transparent Overlays (1976)



Rubylith Operators (1970)



The original Tape-Out?



# Design Automation Today

## Design:

- High-Level Synthesis
- Logic Synthesis
- Schematic Capture
- Layout
- PCB Design

## Simulation:

- Transistor Simulation
- Logic Simulation
- Hardware Emulation
- Technology CAD
- Field Solvers

## Validation:

- ATPG
- BIST

## Analysis and Verification:

- Functional Verification
- Clock Domain Crossing
- Formal Verification
- Equivalence Checking
- Static Timing Analysis
- Physical Verification

## Mask Preparation:

- Optical Proximity Correction (OPC)
- Resolution Enhancement Techniques
- Mask Generation

# EDA in this Course

- **We will primarily use a Cadence Digital Implementation flow:**
  - RTL Compiler (Genus) – Synthesis tool
  - Encounter (Innovus) – Place and Route
    - Tempus – Static Timing Analysis
    - Voltus – Power and IR Drop
    - QRC – Parasitic Extraction
    - Ccopt – Clock Tree Synthesis
  - Incisive (irun) – Logic Simulation
  - Conformal – Logic Equivalence

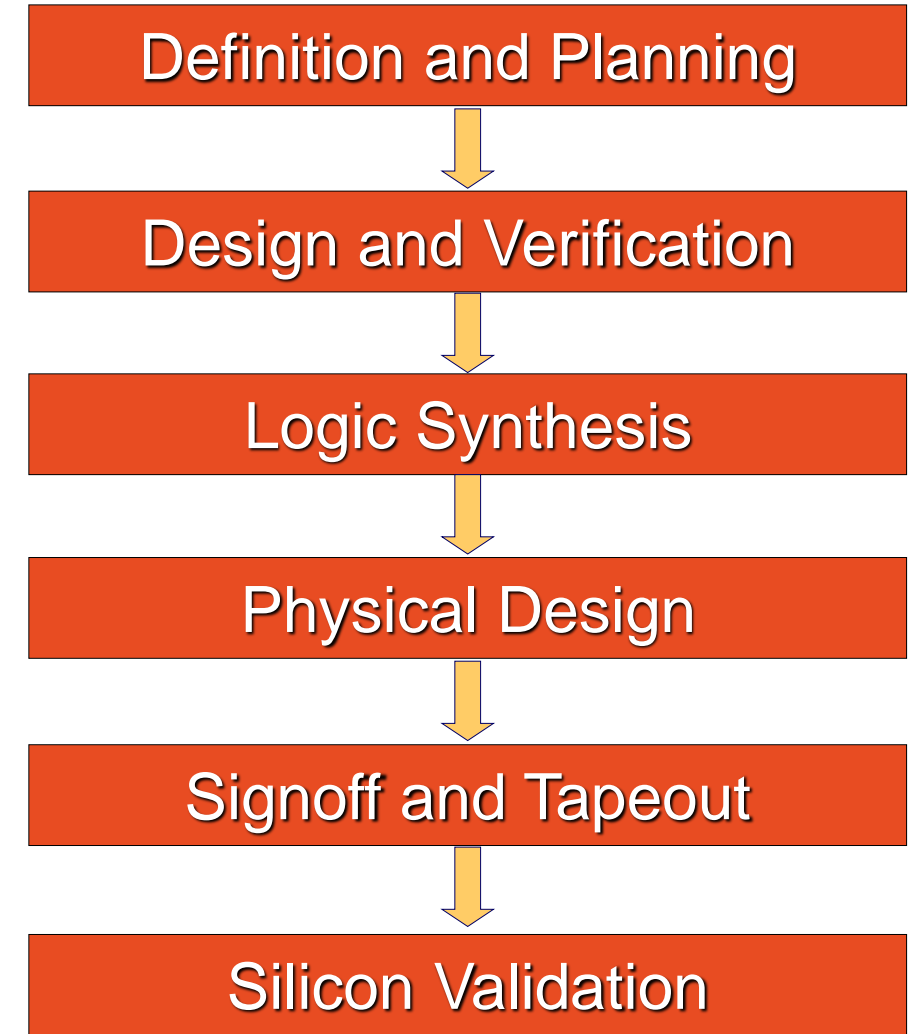




# Chip Design Flow

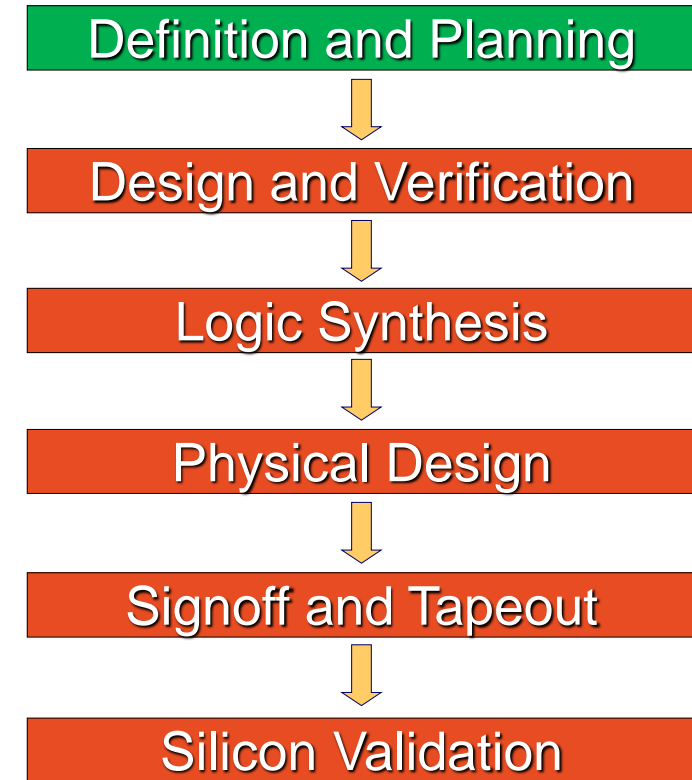
# How a chip is built

- Definition and Planning
  - Design and Verification (Frontend)
  - Logic Synthesis (Frontend and Backend)
  - Physical Design (Backend)
  - Signoff and Tapeout
  - Silicon Validation
- 
- Don't forget package & board design, software design, test plan, etc., etc., etc.



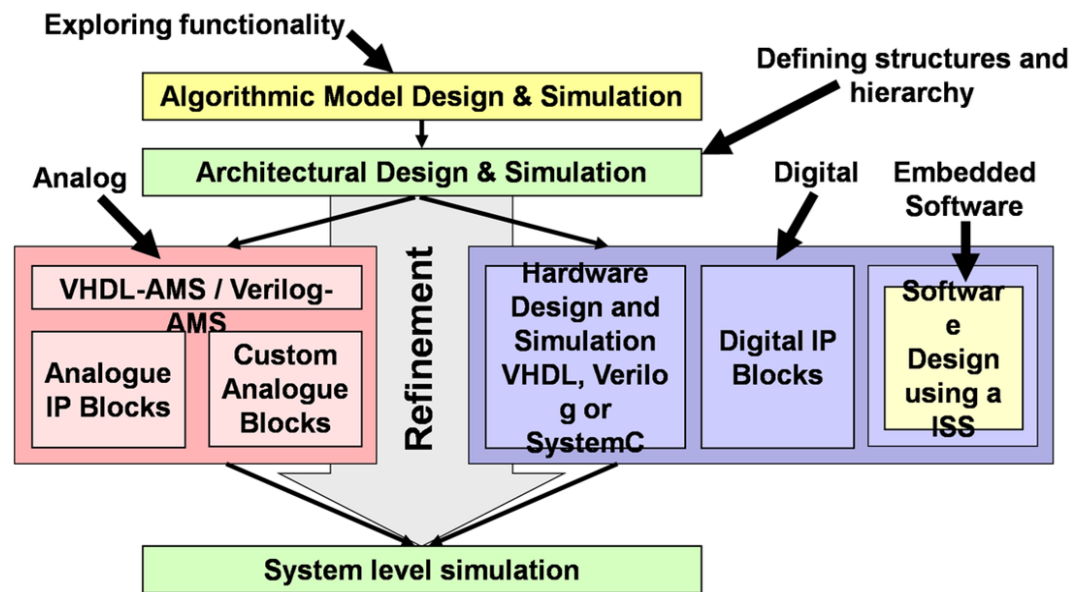
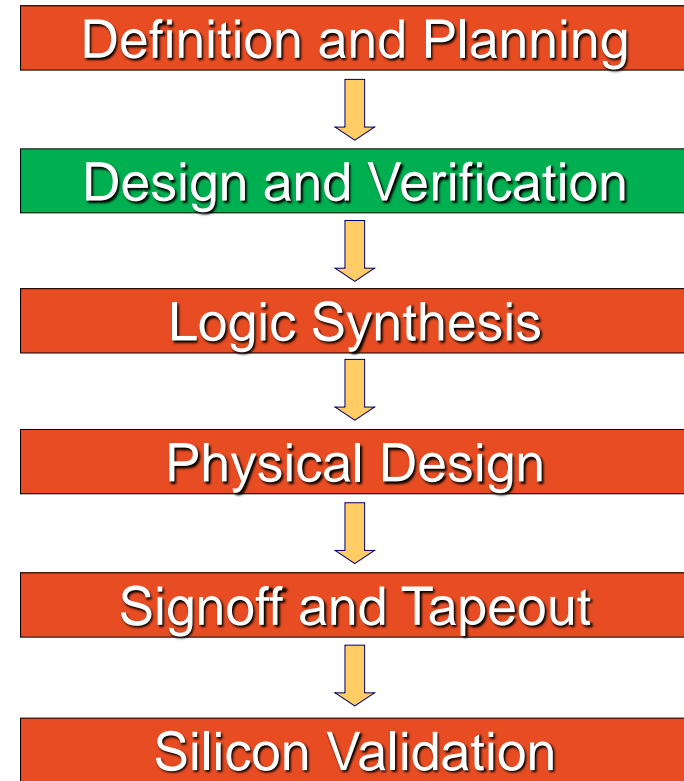
# Definition & Planning

- **Marketing Requirements Document (MRD)**
- **Chip Architecture**
  - Define bus structures, connectivity
  - Partition Functionality
  - High-Level System Model (Bandwidths, Power, Freq.)
  - System partitioning (HW vs SW, #Cores, Memories...)
- **Design Documents**
- **Floorplan/Board Requirements**
- **Process and fab**
- **Project kick-off – transfer to implementation**



# Design and Verification

- RTL (Register Transfer Level) Design
- Integration/Development of IPs
- RTL Lint/synthesability checks
- Formal Verification
- Functional verification all the IPs:
  - unit level
  - sub-system level
  - chip (SOC) level



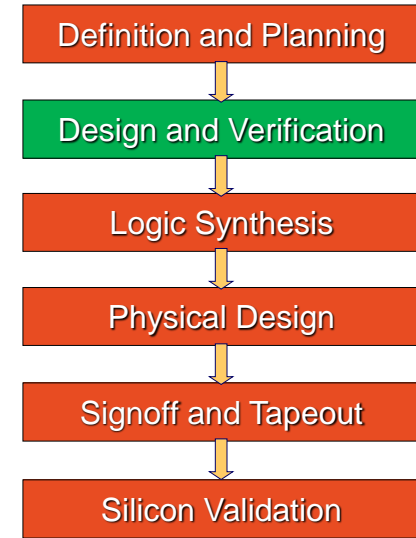
# Design and Verification - IP Integration

- **Hard IP**

- IP provided as pre-existing layouts with:
  - Timing models
  - Layout abstracts
  - Behavioral models (Verilog/VHDL)
  - Sometimes with Spice models, full-layouts
- This is the standard delivery format for custom digital blocks
  - RAMs, ROMs, PLLs, Processors

- **Soft IP**

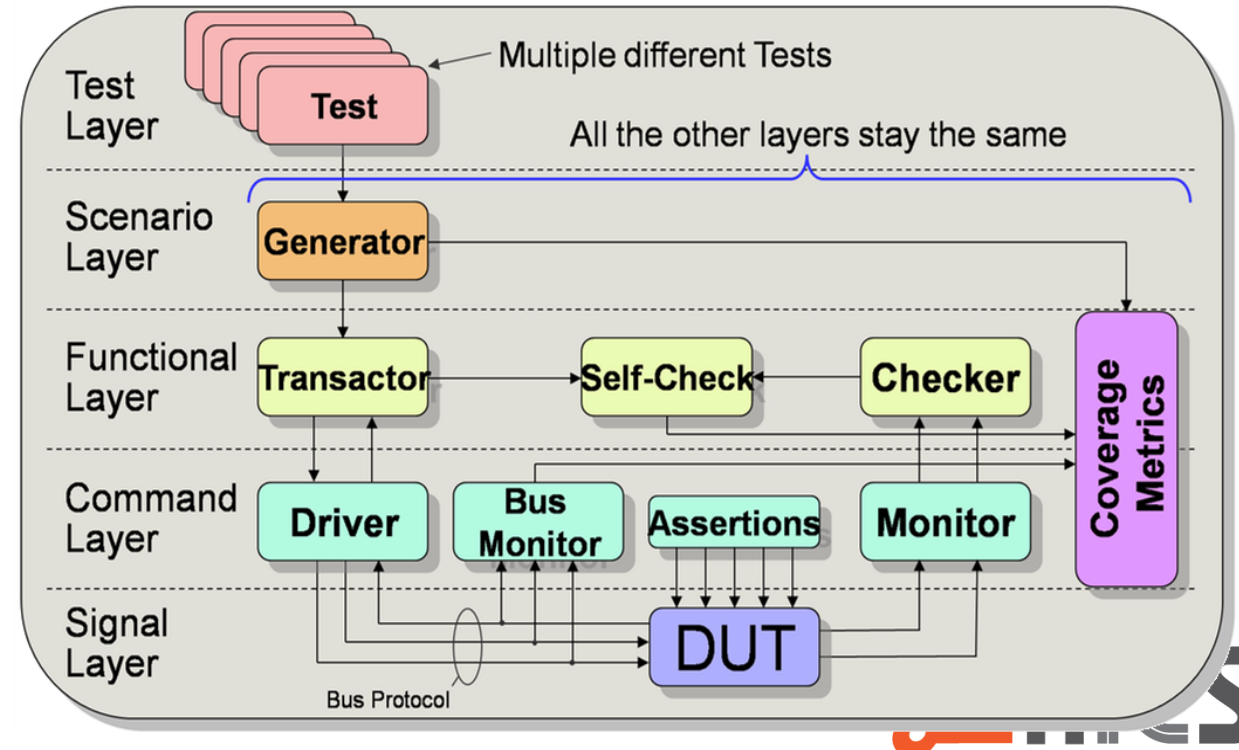
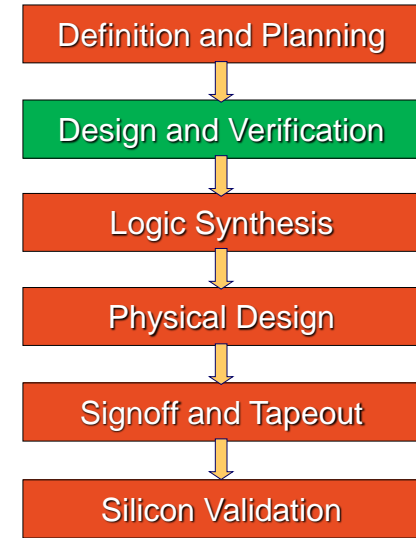
- RTL Code
  - Can be encrypted
  - Instantiated just like any other RTL block
- Sometimes with behavioral models





# Design and Verification - Prototyping

- **Different levels of verification:**
  - Specification driven testing
  - Bug driven testing
  - Coverage driven testing
  - Regression
- **FPGA Prototyping:**
  - Synthesize to FPGA
  - Speeds up testing where possible.
- **Hardware Emulation:**
  - Big servers that can emulate the entire design.



# Logic Synthesis

- **Inputs:**

- Technology library file
- RTL files
- Constraint files (SDC)
- DFT definitions

- **Output:**

- Gate-level netlist

- **Synthesis**

- Converting RTL code into a generic logic netlist

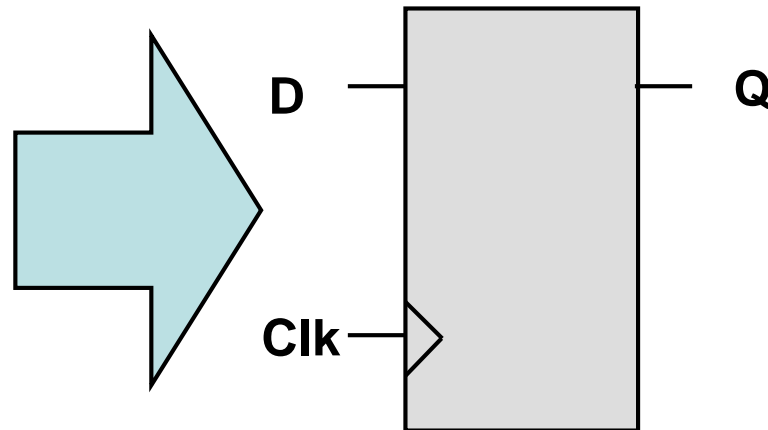
- **Mapping**

- Mapping generic netlist into standard cells from the core library

- **Optimization**

- To meet Timing / Area / Power constraints

```
module DFF(Clk, D, Q);  
  input Clk;  
  input D;  
  output Q;  
  always @(posedge Clk)  
    Q <= D;  
endmodule
```



- **Post Synthesis checks**

- Gate-level simulation
- Formal verification (Logic Equivalence)
- Static Timing Analysis (STA)
- Power/Area estimation

Definition and Planning

Design and Verification

Logic Synthesis

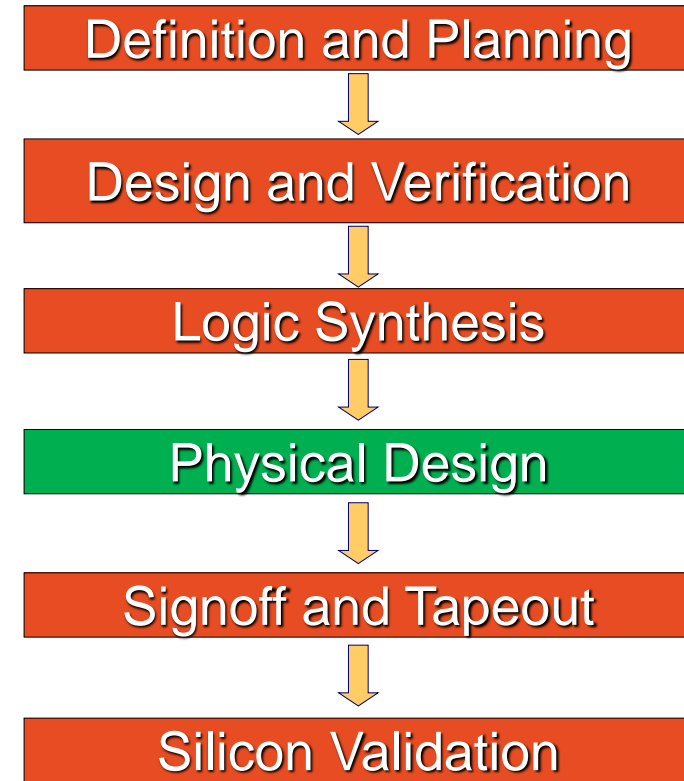
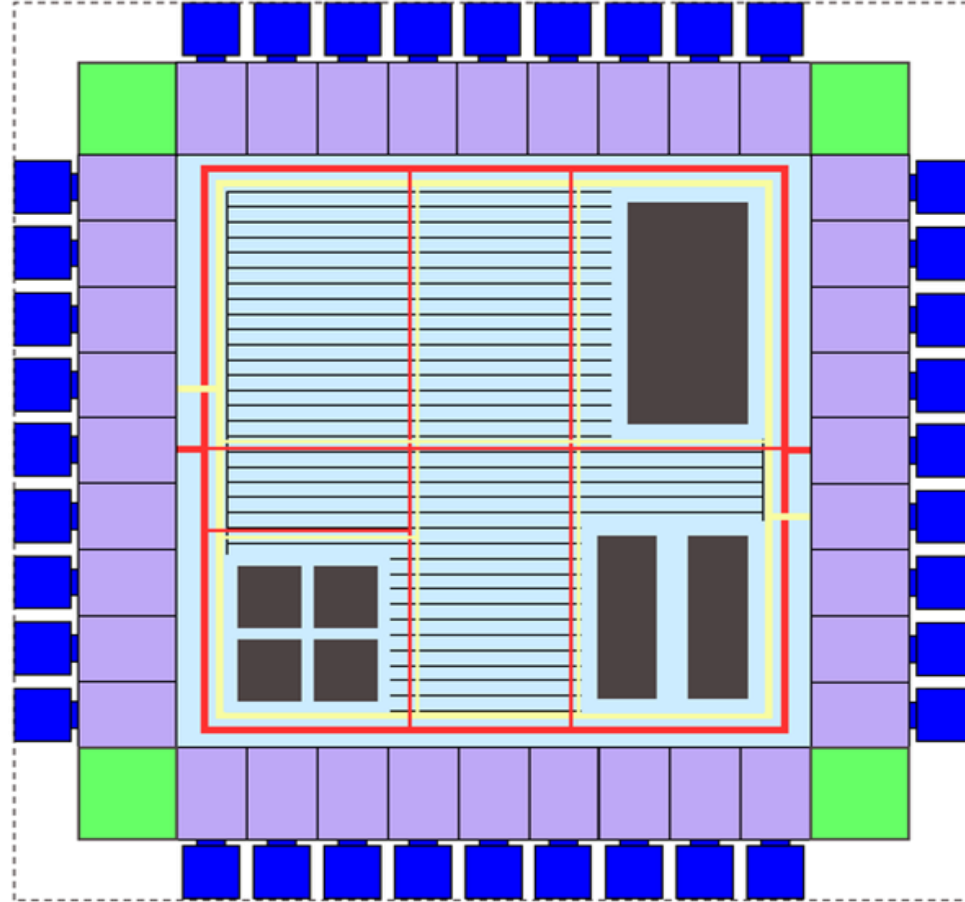
Physical Design

Signoff and Tapeout

Silicon Validation

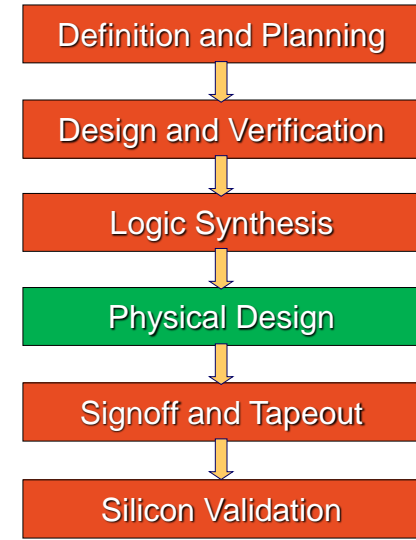
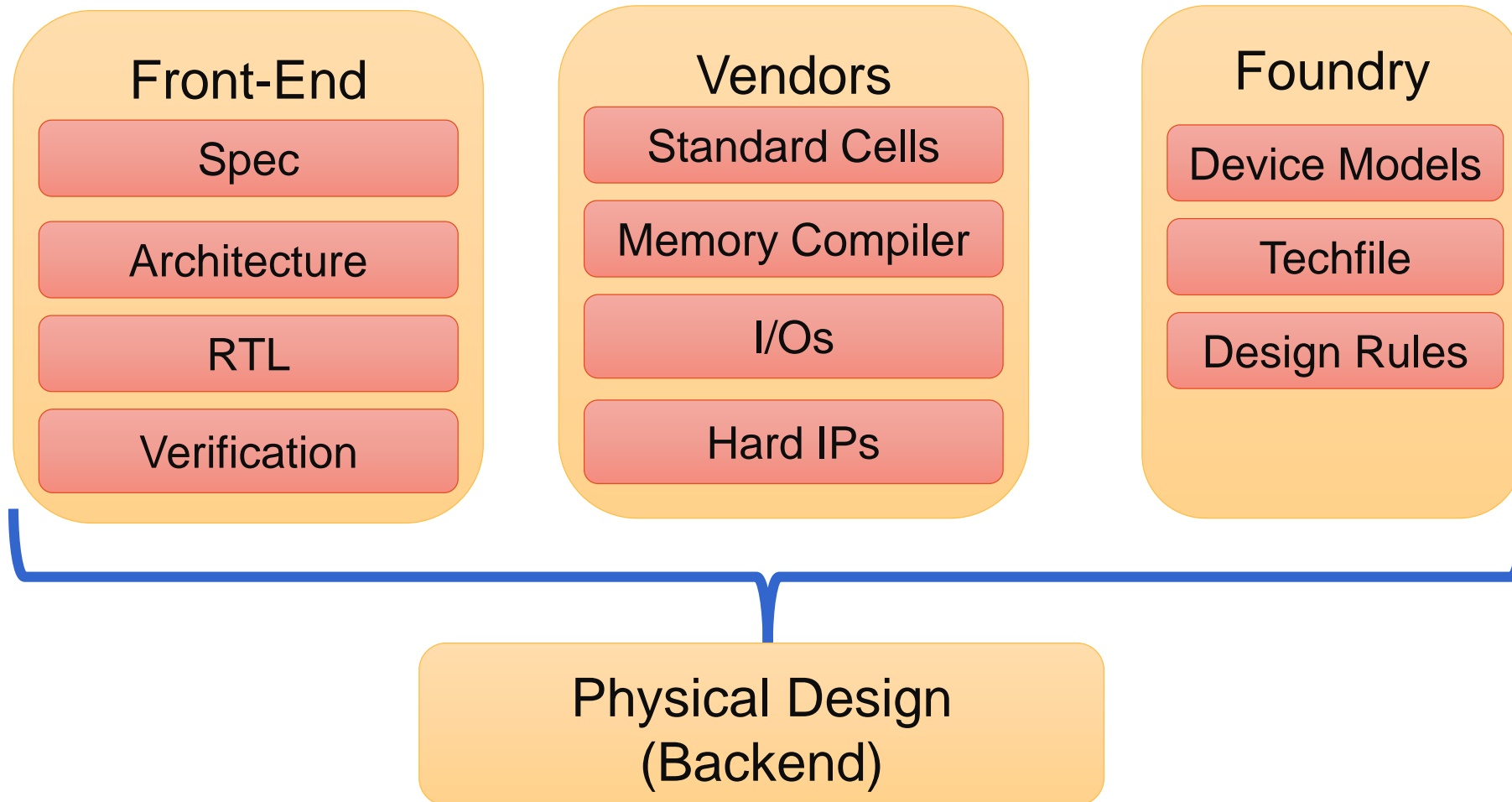
# Physical Design (Backend)

- Floorplan
- I/O Ring
- Power Plan
- Placement
- Clock Tree Synthesis
- Route
- DRC, LVS, Antennas, EM
- LEC, Post-layout

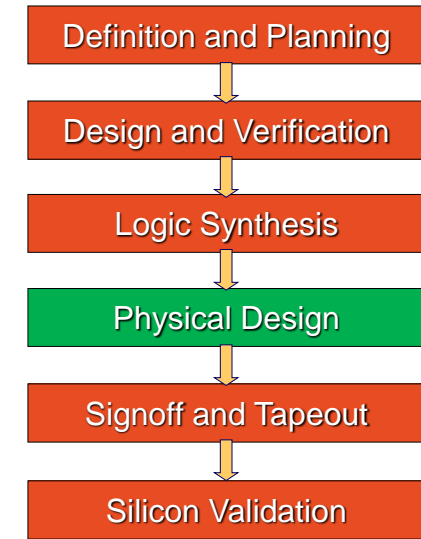
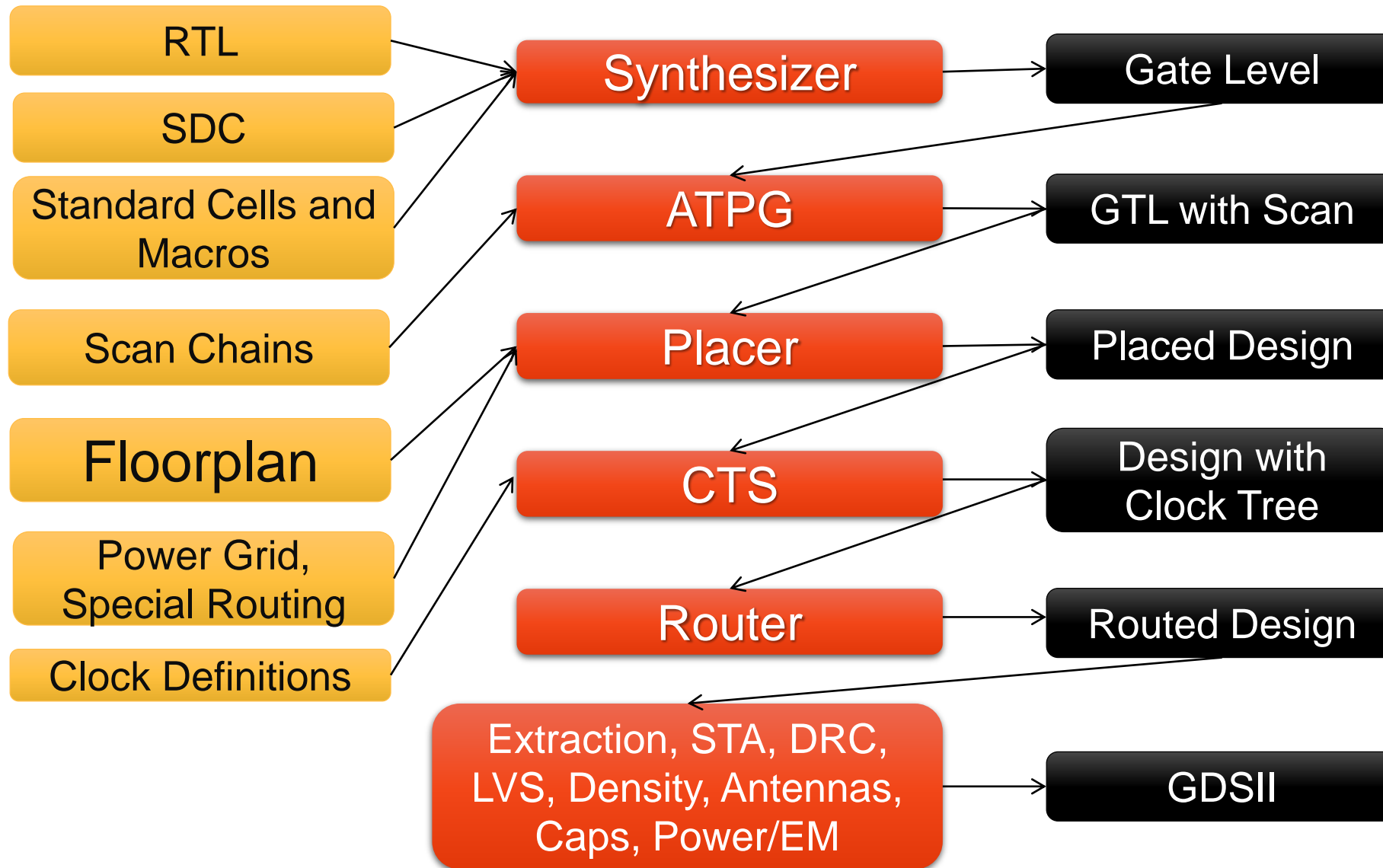


# Physical Design – Backend Flow

- Physical Implementation Inputs

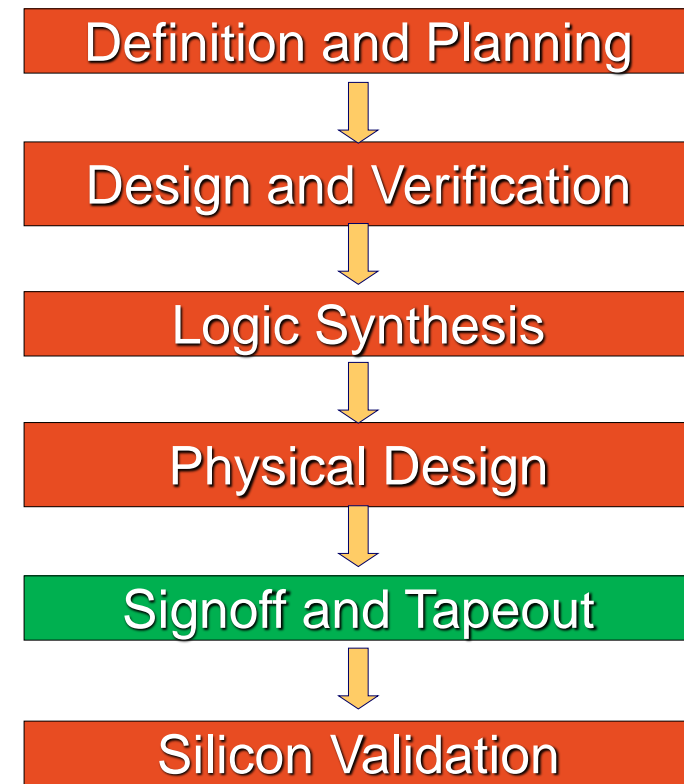


# Physical Design – Backend Flow



# Signoff and Tapeout

- Parasitic Extraction
- STA with SI
- DRC/LVS/ERC/DFM
- Post-layout Gate-level Simulation
- Power Analysis
- DFT
- Logic Equivalence



# Glossary

- **Just to cover most of the terminology of today's lesson:**

- RTL
- GTL
- CAD
- EDA
- DFT (ATPG, Scan, BIST)
- OPC
- Frontend
- Backend
- Verification
- Signoff
- Tapeout
- Hard IP
- Soft IP
- FPGA
- Emulation
- Lint
- Formal Verification
- STA
- SDC
- SI
- DRC, LVS, EM
- GDSII

Special Thanks to:  
Nir Sever  
IDESIA Digital Course  
Marvell Israel  
For the knowledge and materials  
required for preparing this lecture.